

Title (en)

High density, controlled impedance connector.

Title (de)

Impedanz-kontrollierter Verbinder mit hoher Packungsdichte.

Title (fr)

Connecteur haute densité à impédance contrôlée.

Publication

EP 0212764 A2 19870304 (EN)

Application

EP 86300288 A 19860117

Priority

US 76270685 A 19850805

Abstract (en)

A high density electrical connector is shown in which discrete dielectric wafers mount several contact elements within grooves on a first surface of the wafer while mounting a single ground plane within a recess on a second surface. This configuration, when the wafers are stacked side-by-side, forms the contacts in a stripline connection in which the impedance of each contact may be controlled. The wafers may be inserted into slots within a housing to form a high density connector for joining a daughter board to a mother board.

IPC 1-7

H01R 23/68; **H01R 13/658**

IPC 8 full level

H01R 12/04 (2006.01); **H01R 12/16** (2006.01); **H01R 13/658** (2006.01); **H01R 13/72** (2006.01)

CPC (source: EP)

H01R 12/00 (2013.01); **H01R 12/721** (2013.01); **H01R 13/6587** (2013.01)

Cited by

EP0836756A4; EP1420480A3; EP0614202A3; US5702258A; EP0365179A1; US6379188B1; WO02065590A1; WO9736349A1; US10720721B2; US8734185B2; US9722366B2; US8231415B2; US9831605B2; US7887371B2; US8123563B2; US8382524B2; US8591257B2; US10186814B2; US11336060B2

Designated contracting state (EPC)

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DOCDB simple family (application)

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